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Thin Films Prepared by Wet-Chemical Solution Processes

Guest Editor:

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Deadline for manuscript submissions:
closed (31 December 2021)

Message from the Guest Editor

Dear Colleagues,

Thin-film materials have been used in various electronic and energy applications, such as thin-film transistors, sensors, solar cells, and batteries. The fabrication of thin films can be achieved using vacuum-assisted and solution-processed techniques. In this Special Issue, the interests center around wet-chemical solution processes. Materials chemistry and physics for thin-film processing can be represented with a variety of purposes. In particular, ink chemistry for printed electronics, sol–gel processing, and metallo-organic deposition (MOD) techniques are welcomed. In addition, thin-film growth mechanisms should be suggested and demonstrated.

It is my pleasure to invite you to submit a manuscript for this Special Issue. Full papers, communications, and reviews are all welcome.

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Message from the Editor-in-Chief

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